

(0.80 mm) .0315"

CLE SERIES

COST-EFFECTIVE MICRO SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?CLE

Insulator Material: Black Liquid Crystal Polymer

Contact Material: BeCu

Plating: Au over 50 μ" (1.27 μm) Ni

Current Rating (CLE/FTE): 2.7 A per pin (2 pins powered)

Operating Temp Range: -55 °C to +125 °C

Insertion Depth: Top Entry = (1.73 mm) .068" to (3.18 mm) .125" with (0.38 mm) .015" wipe, or pass-through

Bottom Entry = (3.23 mm) .127" minimum plus board thickness

Normal Force: 75 grams (0.73 N)

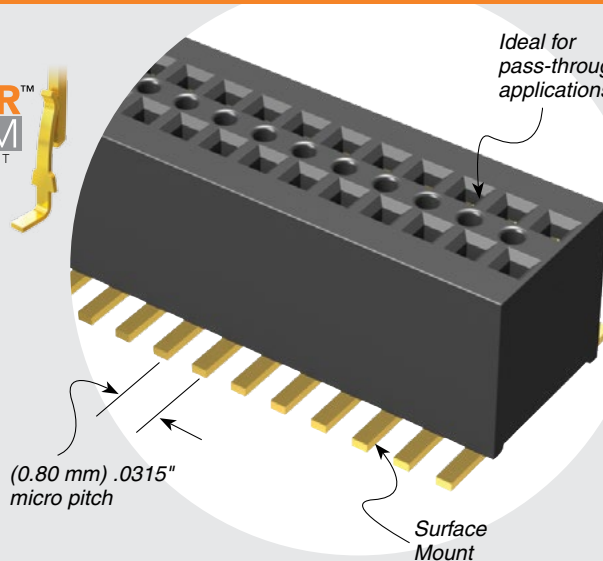
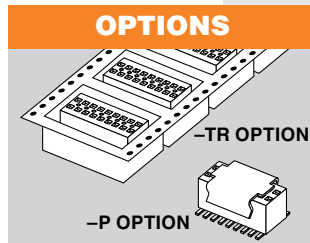
Max Cycles: 100 with 10 μ" (0.25 μm) Au

RoHS Compliant: Yes

Mates with:
FTE, AW



Ideal for pass-through applications



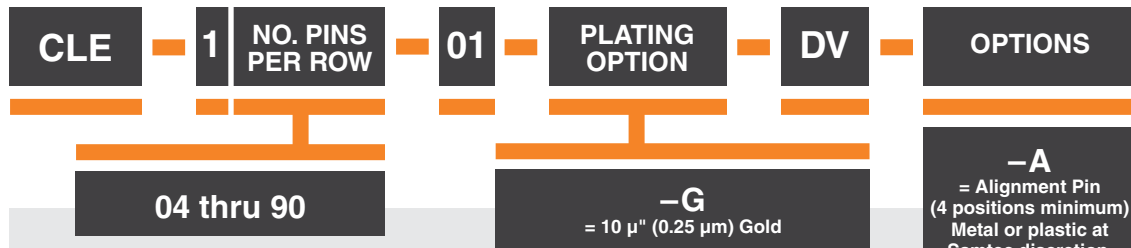
PROCESSING

Lead-Free Solderable: Yes

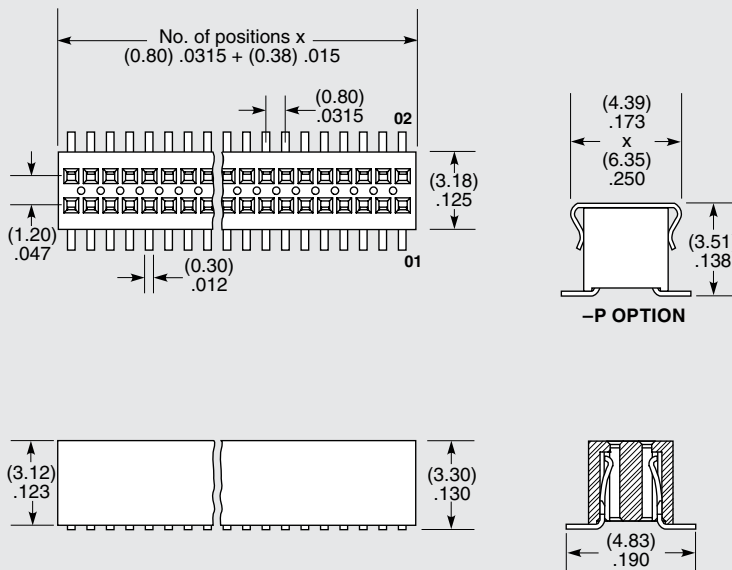
SMT Lead Coplanarity: (0.10 mm) .004" max (04-65) (0.15 mm) .006" max (66-90)*
*(.004" stencil solution may be available; contact IPG@samtec.com)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



- A = Alignment Pin (4 positions minimum) Metal or plastic at Samtec discretion.
- K = (3.50 mm) .138" DIA Polyimide film Pick & Place Pad (8 positions minimum)
- P = Metal Pick & Place Pad (8 positions minimum)
- TR = Tape & Reel Packaging



Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.